CLAIMS

1. A method of manufacturing a tape (T) to which a plurality of elements (C) are affixed by means of a glue in a solid state, the method comprising a gluing step, in which elements (C) are glued to a basic tape (T) by means of a glue in a liquid state so as to obtain a glued tape, the method being characterised in that the gluing step is followed by:

- a winding step, in which the glued tape (T) is wound while the glue is in a state between the liquid state and the solid state, so as to obtain a winded glued tape; and
- a heating step, in which the winded glued tape is heated, so that the glue reaches the solid state.

2. The method according to claim 1, characterized in that in the winding step, the glued tape (T) is wound on reel (R) made of composite material.

3. The method according to claim 2, characterized in that the reel (R) has a diameter bigger than 600 mm.

4. The method according to claim 3, characterized in that the reel (R) is made of fiberglass impregnated with epoxy resin.

5. A method of manufacturing a smart card, characterized in that the method comprises the following steps:

- a gluing step, in which semiconductor devices (C) are glued to a basic tape (T) by means of a glue in a liquid state so as to obtain a glued tape;
- a winding step, in which the glued tape (T) is wound while the glue is in a state between the liquid state and the solid state, so as to obtain a winded glued tape;
- a heating step, in which the winded glued tape is

heated, so that the glue reaches the solid state ;

- a cutting step, in which the tape (T) is cut so as to obtain modules (MOD); and
- an embedding step, in which a module (MOD) is embedded in a cardbody (CB) so as to obtain a smart card.